

**REMARKS**

In order to expedite the prosecution of the present application, this Request for Continued Examination is being filed in order to further define the claimed invention. Specifically speaking, previously presented Claim 1 now recites that the silane coupling agent has a hydroxyl group in its molecule and is obtained by reaction of an imidazole compound and 3-glycidoxypropyltrimethoxysilane or is obtained by a reaction of an imidazole compound and 3-methacryloxypropyltrimethoxysilane and Claims 4 and 10 have been canceled. The imidazole/organic monocarboxylic acid salt derivative reaction product of Kumagai has a structure of a monocarboxylic acid group attached to a reaction product obtained by reacting an imidazole compound with a silane compound having a glycidoxy group. As such, the compound (C) in the current claims is not limited to the Kumagai imidazole/organic monocarboxylic acid salt derivative reaction product.

Even though Kumagai teaches the addition of an imidazole/organic monocarboxylic acid salt derivative reaction product in order to improve the adhesion and strength of the resin, there is no guarantee that compound (C) of the present invention would promote the curing of these resins, improve the adhesion to metals, inorganic materials and organic materials and improve the corrosion resistance. These improvements in the resin properties are not suggested in any of the prior art cited by the Examiner and, therefore, clearly establishes the patentability of the presently claimed invention thereover. Favorable consideration is respectfully solicited.

Respectfully submitted,

  
Terryence F. Chapman

TFC/smd

FLYNN, THIEL, BOUTELL  
& TANIS, P.C.  
2026 Rambling Road  
Kalamazoo, MI 49008-1631  
Phone: (269) 381-1156  
Fax: (269) 381-5465

David G. Boutell	Reg. No. 25 072
Terryence F. Chapman	Reg. No. 32 549
Mark L. Maki	Reg. No. 36 589
Liane L. Churney	Reg. No. 40 694
Brian R. Tumm	Reg. No. 36 328
Heon Jekal	Reg. No. 64 219
Eugene J. Rath, III	Reg. No. 42 094
Dale H. Thiel	Reg. No. 24 323
Sidney B. Williams, Jr.	Reg. No. 24 949

Encl: None

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